

Tool ID: 222  
Tool Location: 111

Equipment Information Sheet  
**YES EcoClean Asher**

**Manager:** Aaron Windsor  
**Backup:** Tom Pennell

607-254-4831  
607-254-4309

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- Wafers may be hot after processing. Tool has an automatic 60 second delay before door is unlatched.

**USAGE RESTRICTIONS**  
**SCHEDULING/SIGN-UP RESTRICTIONS**

Minimum Tool Time: 15 minutes

Contact the tool manager to schedule if you want to process wafers other than 4"

**MATERIALS COMPATIBILITY CATEGORY**

Tool Category 2: Silicon Based Substrates and Select Refractory Metals	
Allowed	Not Allowed
Tool category 1/1E materials	No Glass Substrates
Silicon Based Materials only	No CNF Class A or Class B metals and oxides/compounds of (exposed or buried) (ie Magnesium, Zinc, Barium, Calcium)
Si, SiC, SiO <sub>2</sub> substrates	
All Furnace grown or deposited films	
PECVD Films	No Gold, Silver or Copper (Exposed or buried)
ALD dielectric films	No High Vapor pressure materials
<b>CNF Refractory Metals (ie Al, Ti,Ta,W,Pt,Mo,Cr,Ni)</b>	No III/V Compound Semiconductors
Nitrides and Oxides of above metals	No Organic/Biology Molecules prepared-with or without Salt buffers
Cured organics and baked Photoresist	

**High Vapor Pressure Metals and Compounds**are materials that have a vapor pressure above 1e-6 Torr at 400 C.

**Additional Material Restrictions and Exceptions**

- No SU-8
- III/V substrates allowed.

Last Updated: 02/19/2024